



# Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model

[List multiple models if applicable.]

HP ProBook 450 G1 Notebook PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm Mother Board, SD Board, USB Board, ODD board, Function Board	5
Batteries	All types including standard alkaline and lithium coin or button style batteries Main battery, RTC battery	2
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries NO	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps Panel	1
Cathode Ray Tubes (CRT)	NO	0
Capacitors / condensers (Containing PCB/PCT)	NO	0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	NO	0
External electrical cables and cords	NO	0
Gas Discharge Lamps	NO	0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	NO	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations. NO	0
Components and waste containing asbestos	NO	0
Components, parts and materials containing	NO	0

refractory ceramic fibers		
Components, parts and materials containing radioactive substances	NO	0

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Cross screwdriver	#1
Description #2 P1 screwdriver	#1
Description #3	
Description #4	
Description #5	

## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

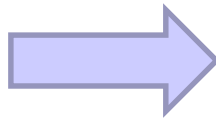
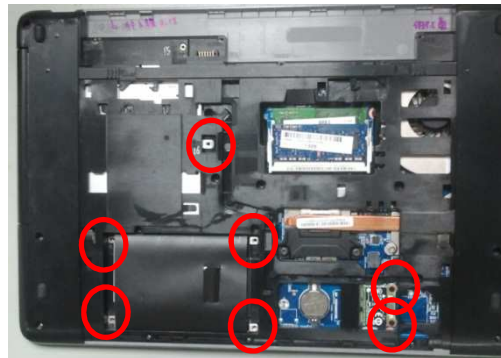
1. Take off the battery package from system bottom side.
2. Release DIMM/HDD door knob and take off DIMM/HDD door.
3. Loose HDD & ODD module screws and take off HDD & ODD module from system.
4. Loose WLAN/WWAN screws and take off WLAN/WWAN, DIMM module from system.
5. Loose KB module screw, and then take off KB module.
6. Loose L-case to U-case screws on bottom side & U-case to L-case screw on top side, and take off U-case from system.
7. Loose the screw of the speaker ,power board, function board, touchpad module, FPR, SD board ,and USB board then take off them.
8. Loose screw of hinge to L-case, take off LCD module from L-case.
9. Loose screw of MB to U-case, take off MB. Loose screw of thermal module from MB, take off thermal module
10. Loose screw and screw mylar, take off hinge cover and lcd bezel.
11. Loose LCD & Hinge screw, take off LCD , hinge and panel.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

## Disassembly Process-1

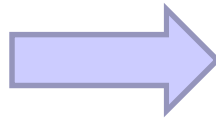


Take off the battery package from system bottom side. Release DIMM/HDD door knob and take off DIMM/HDD door.

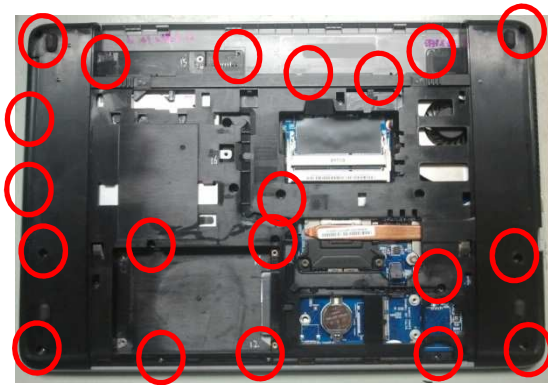


Loose HDD & ODD module screws and take off HDD & ODD module from system.  
Loose WLAN/WWAN screws and take off WLAN/WWAN, DIMM module from system.

## Disassembly Process-2



Loose KB module screw, and then take off KB module.



Loose L-case to U-case screws on bottom side & U-case to L-case screw on top side, and take off U-case from system.

## Disassembly Process-3



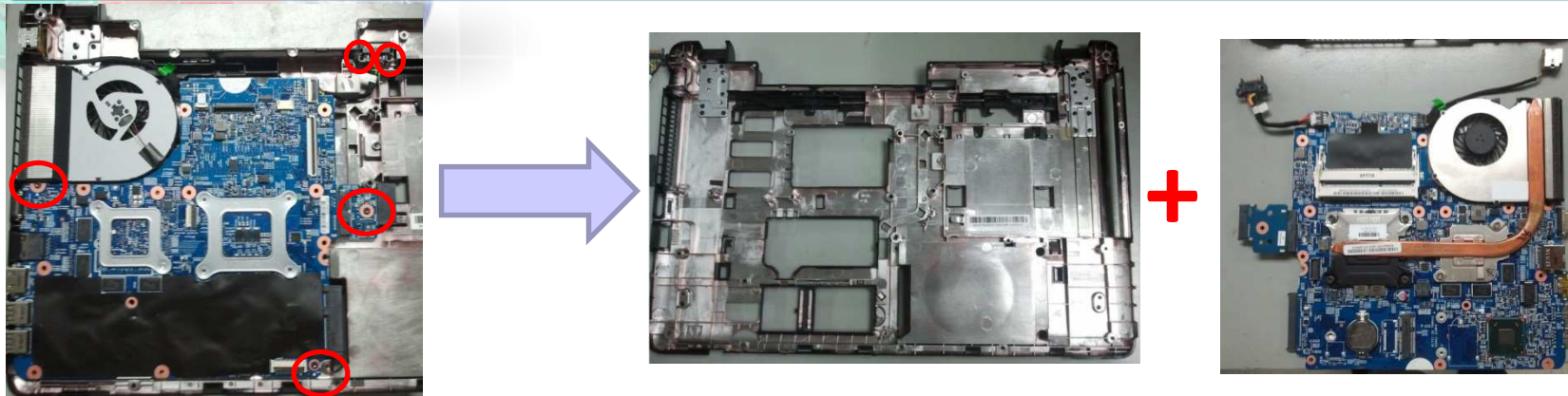
Loose the screw of the speaker ,power board, function board, touchpad module, FPR, SD board ,and USB board then take off them.



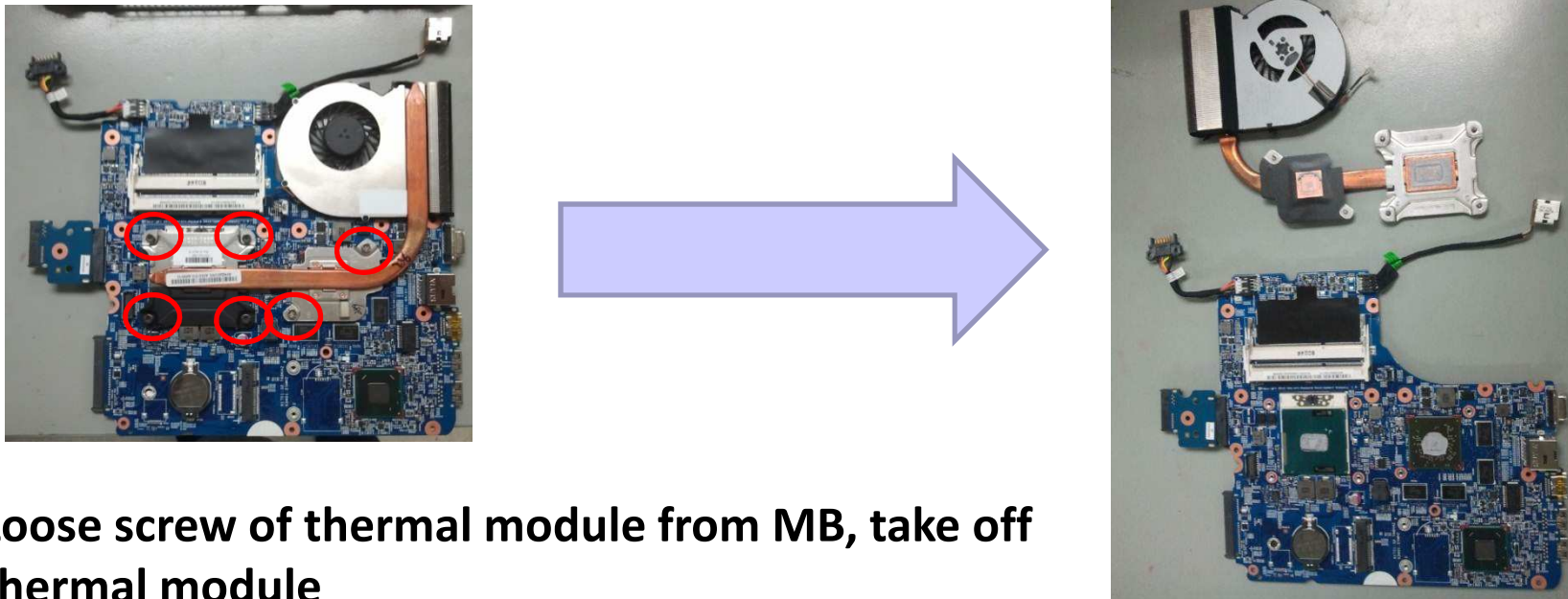
Loose screw of hinge to L-case, take off LCD module from L-case.



## Disassembly Process-4



Loose screw of MB to U-case, take off MB.



Loose screw of thermal module from MB, take off thermal module

## Disassembly Process-5



Loose screw and screw mylar, take off hinge cover and lcd bezel.



Loose LCD & Hinge screw, take off LCD , hinge and panel.

